EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	37735	("205"/$.ccls. "204"/$.ccls.) and (electrolysis electrolytic electrochemic$4 plating electrodeposit$5 electroplat$5) and (apparatus system chamber tool)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 10:12
S2	6389	("204"/198-241.ccls.) and (electrolysis electrolytic electrochemic$4 plating electrodeposit$5 electroplat$5) and (apparatus system chamber tool)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 10:14
S3	686	("204"/198-241.ccls.) and (electrolysis electrolytic electrochemic$4 plating electrodeposit$5 electroplat$5) and (apparatus system chamber tool) and polishing	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 10:42
S4	2	"6809029".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 10:15
S5	3	("6486055" | "6602787").PN. OR ("6809029").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/01 10:20
S6	101	("204"/198-241.ccls.) and (electrolysis electrolytic electrochemic$4 plating electrodeposit$5 electroplat$5) and (apparatus system chamber tool) and polishing and cup	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 12:05
S7	587	("204"/198-241.ccls.) and (electrolysis electrolytic electrochemic$4 plating electrodeposit$5 electroplat$5) and (apparatus system chamber tool) and $5polishing not S6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 11:14
S8	62	("204"/198-241.ccls.) and (electrolysis electrolytic electrochemic$4 plating electrodeposit$5 electroplat$5) and (apparatus system chamber tool) and $5polishing and (fac$3 near5 (up upward)) with (substrate wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 12:05

S9	10	("20020029961" | "5853559" | "6126798" | "6132587" | "6176992" | "6179982" | "6179983" | "6375823" | "6402925" | "6416647").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/01 11:28
S10	2	("5084149" | "5256274").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/01 12:02
S11	95	("204"/$.ccls.) and (electrolysis electrolytic electrochemic$4 plating electrodeposit$5 electroplat$5) and (apparatus system chamber tool) and $5polishing and (fac$3 near5 (up upward)) with (substrate wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 15:49
S12	2	"6077412".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 15:01
S13	56	("4391694" | "5000827" | "5024746" | "5256274" | "5368711" | "5429733" | "5437777" | "5441629" | "5447615" | "5516414" | "5597460" | "5830805" | "5853559" | "5865984" | "5932076").PN. OR ("6077412").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/01 15:40
S14	5	S13 and electroless and annealing	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/01 15:49
S15	26	("204"/$.ccls.) and (electrolysis electrolytic electrochemic$4 plating electrodeposit$5 electroplat$5) and (apparatus system chamber tool) and $5polishing and (fac$3 near5 (up upward)) with (substrate wafer) and electroless and annealing	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 15:58
S16	108	("204"/$.ccls.) and (electrolysis electrolytic electrochemic$4 plating electrodeposit$5 electroplat$5) and (apparatus system chamber tool) and $5polishing and (substrate wafer) and electroless and annealing	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 15:50

| S17 | 46 | ("5363171" \| "5393624" \| "5658183" \| "5719495" \| "5872633" \| "5924058" \| "5964643" \| "6004047" \| "6017437" \| "6025600" \| "6045618" \| "6051284" \| "6077412" \| "6110011" \| "6122046" \| "6159073" \| "6168693" \| "6187072" \| "6190234" \| "6193802" \| "6194628" \| "6197181" \| "6201240" \| "6208751" \| "6231743" \| "6238539" \| "6244931" \| "6247998" \| "6255222" \| "6270634" \| "6277194" \| "6280289" \| "6283692" \| "6284622" \| "6296548" \| "6303395" \| "6303931" \| "6309276" \| "6318384" \| "6331490" \| "6352467" \| "6444481" \| "6454899" \| "6511898" \| "6534328").PN. OR ("6747734"). URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2006/08/01 16:15 |
| S18 | 1 | S12 and electroless | US-PGPUB; USPAT; USOCR | OR | ON | 2006/08/01 16:16 |